#### 502023830 08/14/2012

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
Osamu Onishi	07/24/2012
Haruo Ikeda	07/24/2012
Nobuo Tagashira	07/24/2012

### RECEIVING PARTY DATA

Name:	Sumitomo Bakelite Co., Ltd.
Street Address:	5-8 Higashi-Shinagawa, 2-Chome Shinagawa-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	140-0002

# PROPERTY NUMBERS Total: 2

Property Type	Number
Application Number:	13550586
PCT Number:	US1246981

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	PLY211-0006B US/UTY
NAME OF SUBMITTER:	Bernard Berman

Total Attachments: 2

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> **PATENT** REEL: 028780 FRAME: 0909

## **ASSIGNMENT**

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in

A SELF-IMAGEABLE LAYER FORMING POLYMER AND COMPOSITIONS THEREOF
(Invention Title)
for which I have this day executed an application for a United States Patent (hereinafter "said application").
AND/OR
X for which an application for a United States Patent was filed on 07/16/2012 (mm/dd/yyy and bears Application Number 13/550,586 (hereinafter "said application").
AND/OR ·
for which an international patent application was filed under the Patent Cooperation Treat on 07/16/2012 (mm/dd/yyyy), bearing Application No. PCT/US2012/46981 (hereinafte "said application").

AND, WHEREAS, Sumitomo Bakelite Co., Ltd., having a place of business at 5-8 Higashi-Shinagawa, 2-Chome Shinagawa-ku, Tokyo, Japan 140-0002, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs,

executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

1. FULL NAME OF ASSIGNOR:	RESIDENCE:
Osamu Onishi	Tokyo, Japan
EXECUTED this 24_day of	, 2012 
***************************************	Signature ************************************
2. FULL NAME OF ASSIGNOR:	RESIDENCE:
Haruo Ikeda	Tokyo, Japan
EXECUTED this 24 day of Joly	Novo Yeda
***************************************	Signature
3. FULL NAME OF ASSIGNOR:	RESIDENCE:
3. FULL NAME OF ASSIGNOR:  Nobuo Tagashira	RESIDENCE: Tokyo, Japan
	Tokyo, Japan
Nobuo Tagashira	Tokyo, Japan
Nobuo Tagashira  EXECUTED this <u>24</u> day of <u>July</u>	Tokyo, Japan , 2012 <u>Nobur Zagoskira</u>
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Checked Box indicates \_ additional page(s) for inventor signatures.